

IN THE ABSTRACT:

Please substitute the attached Abstract for the Abstract now in the application.

ABSTRACT

B2
A method for fabricating a laminate circuit structure is provided. The method comprises: providing at least two modularized circuitized voltage plane subassemblies wherein each of the subassemblies comprise at least two signal planes having an external and internal surface disposed about an internal voltage plane; providing a dielectric material between the signal and voltage planes; and providing dielectric on each external surface of each signal plane; and providing a non-cured or partially cured curable dielectric composition between the subassemblies wherein the dielectric composition comprises, dielectric material that is of the same material as the dielectric material used in said subassemblies, aligning the subassemblies, and then laminating to cause bonding of the subassemblies.
